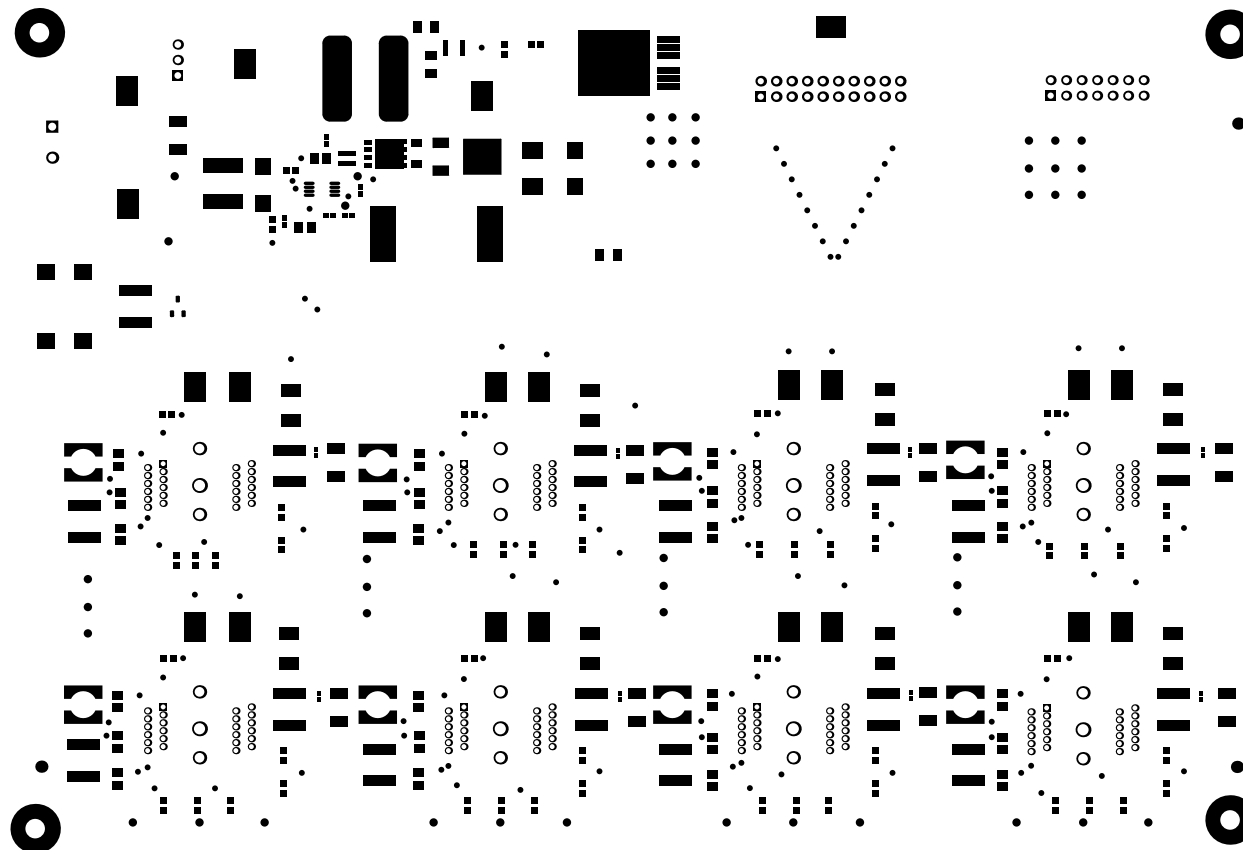
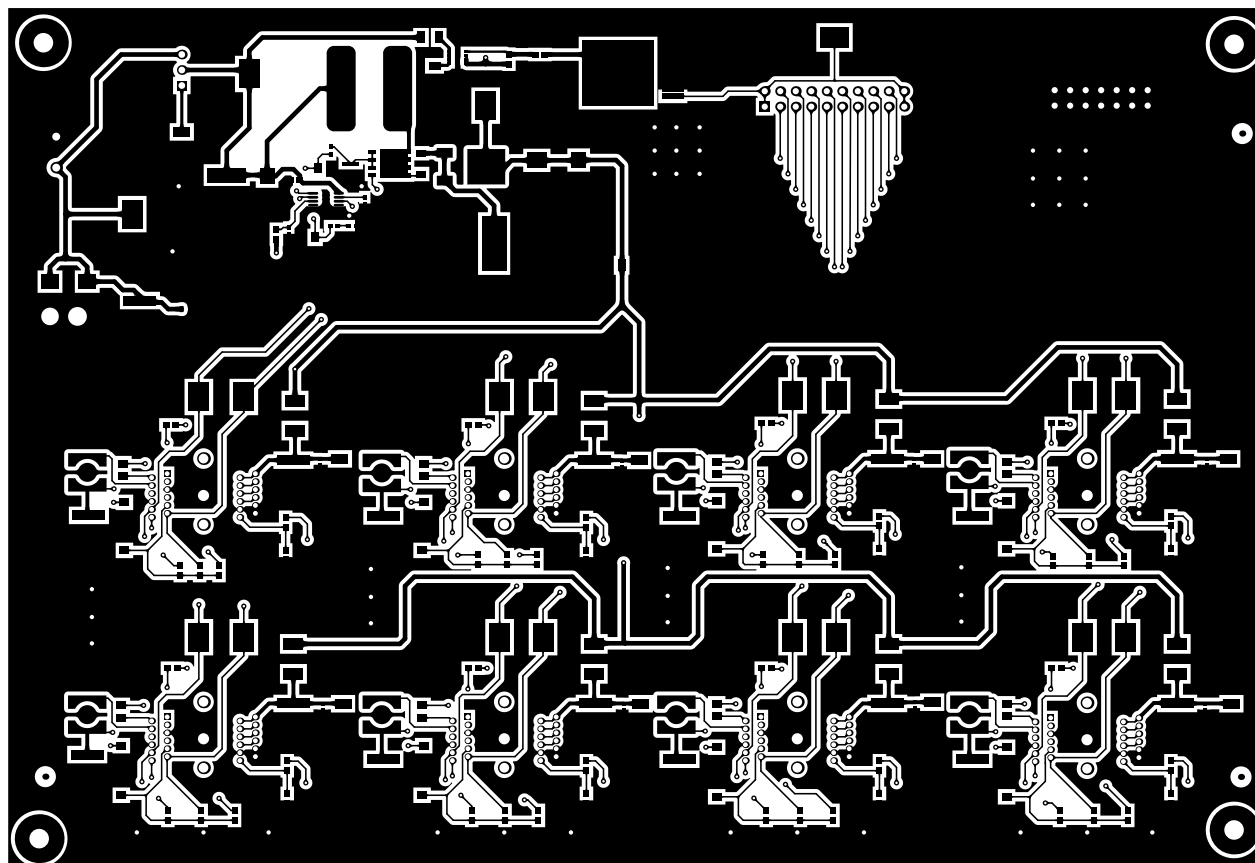


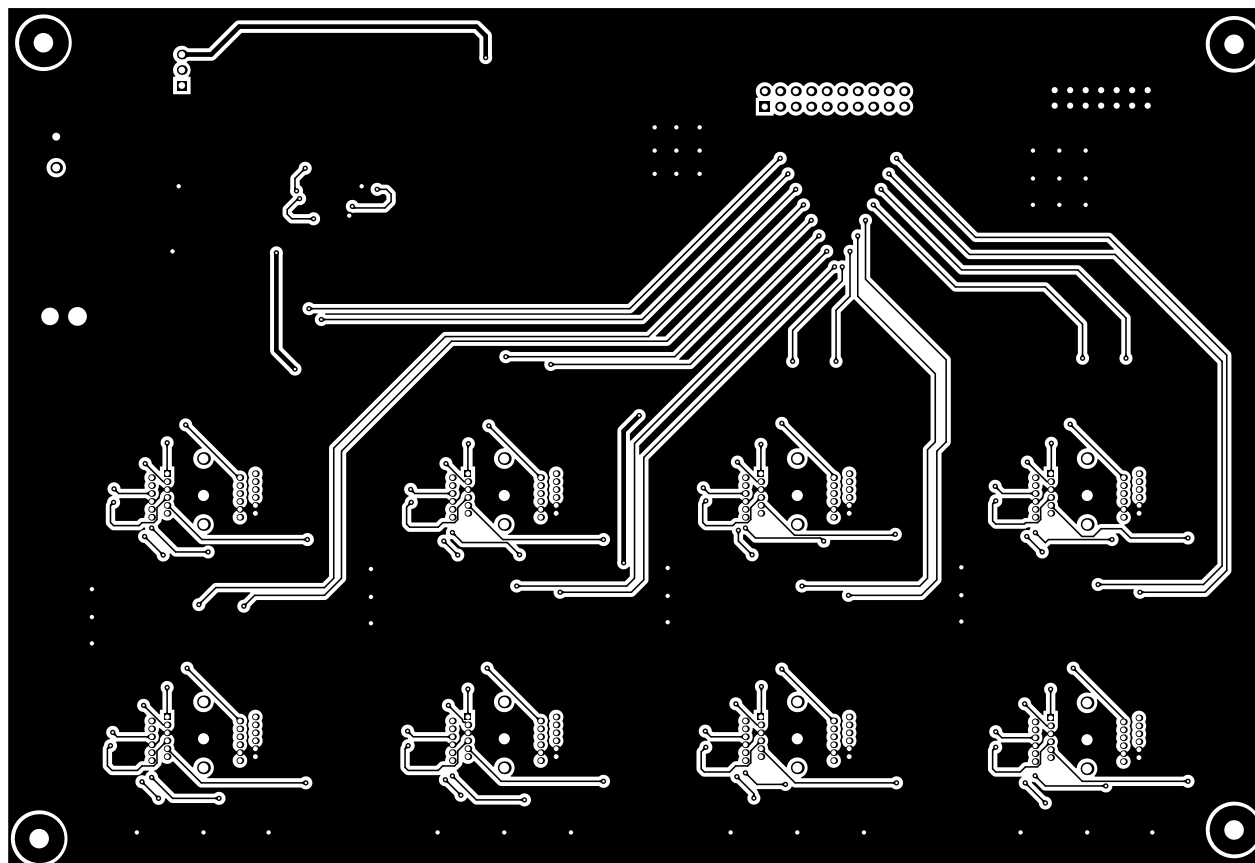
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01373		
PLOT NAME = Top Overlay	GENERATED : 2/3/2017	2:25:41 PM	TEXAS INSTRUMENTS



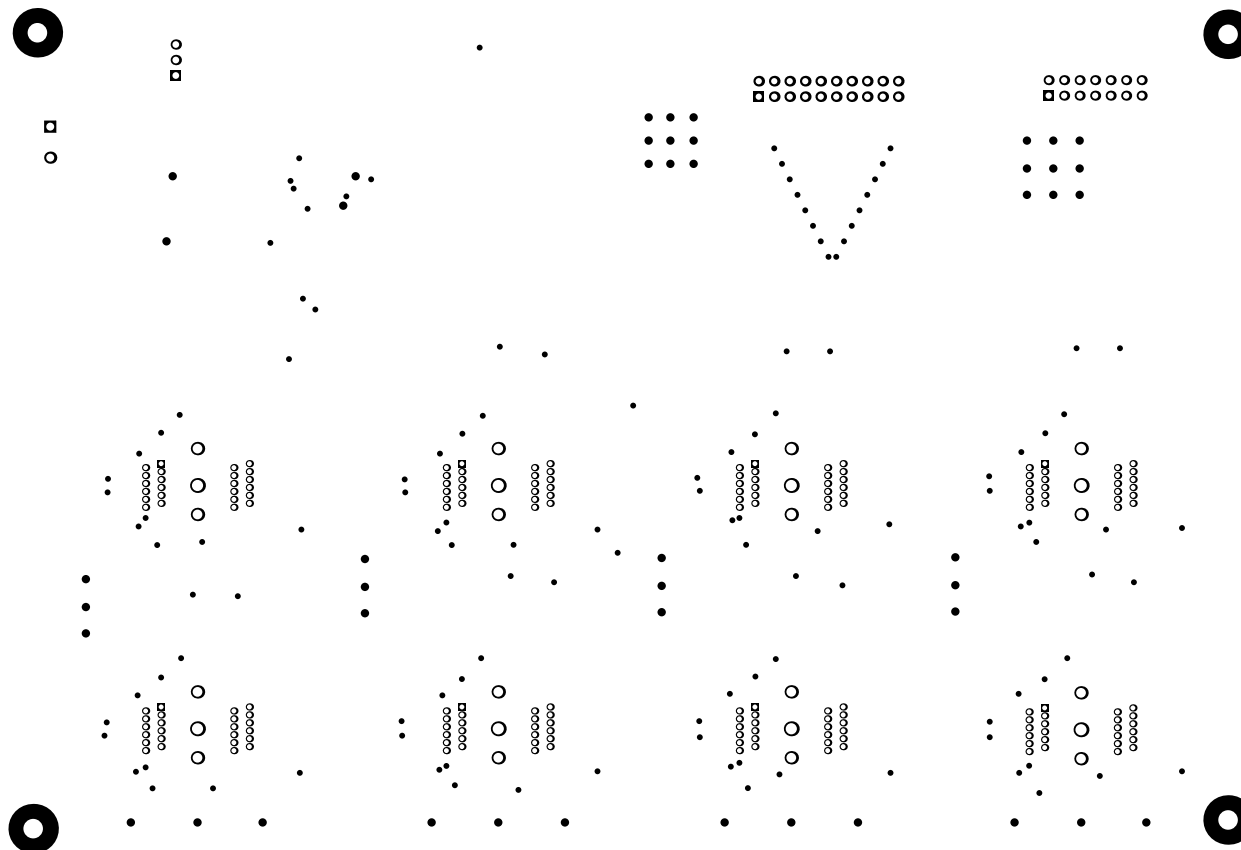
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01373		
PLOT NAME = Top Solder Mask	GENERATED : 2/3/2017	2:25:42 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01373		
PLOT NAME = Top Layer	GENERATED : 2/3/2017	2:25:43 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:	TIDA-01373	
PLOT NAME = Bottom Layer	GENERATED	: 2/3/2017 2:25:44 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01373		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/3/2017	2:25:45 PM	TEXAS INSTRUMENTS

24

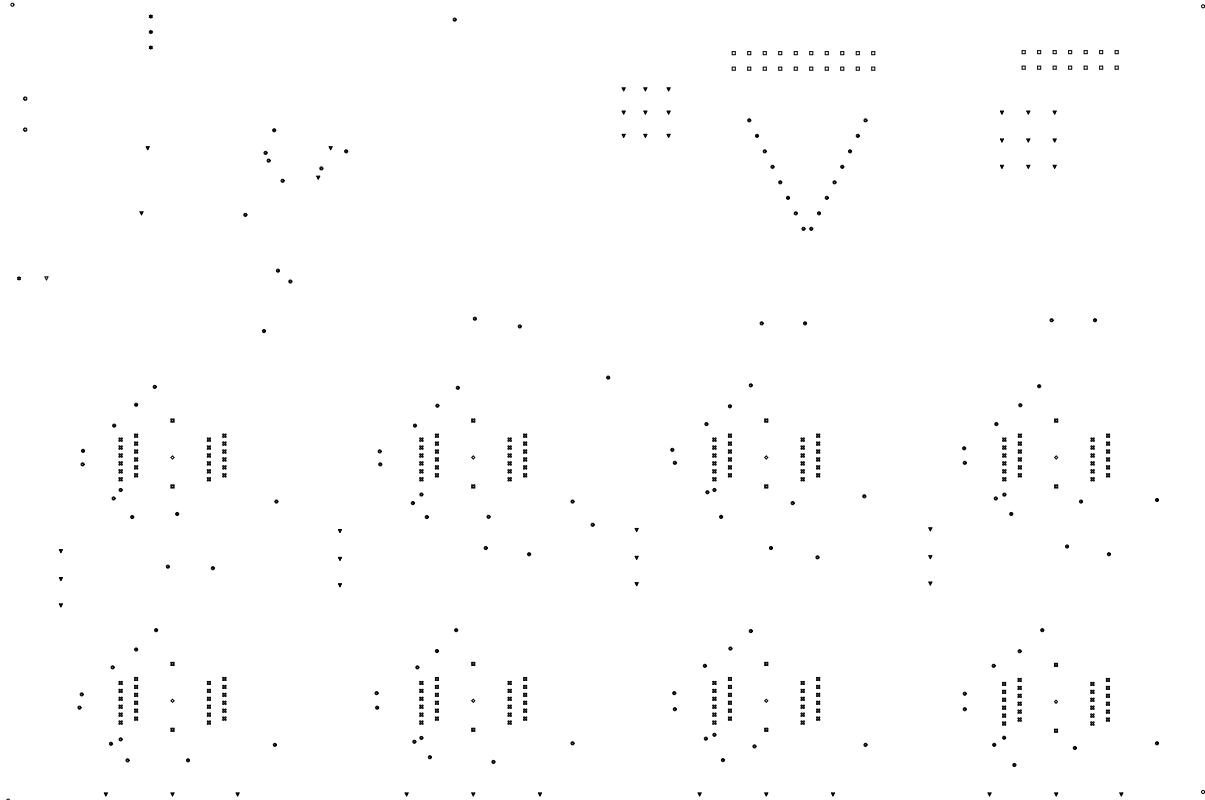
24

24

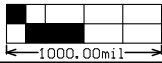
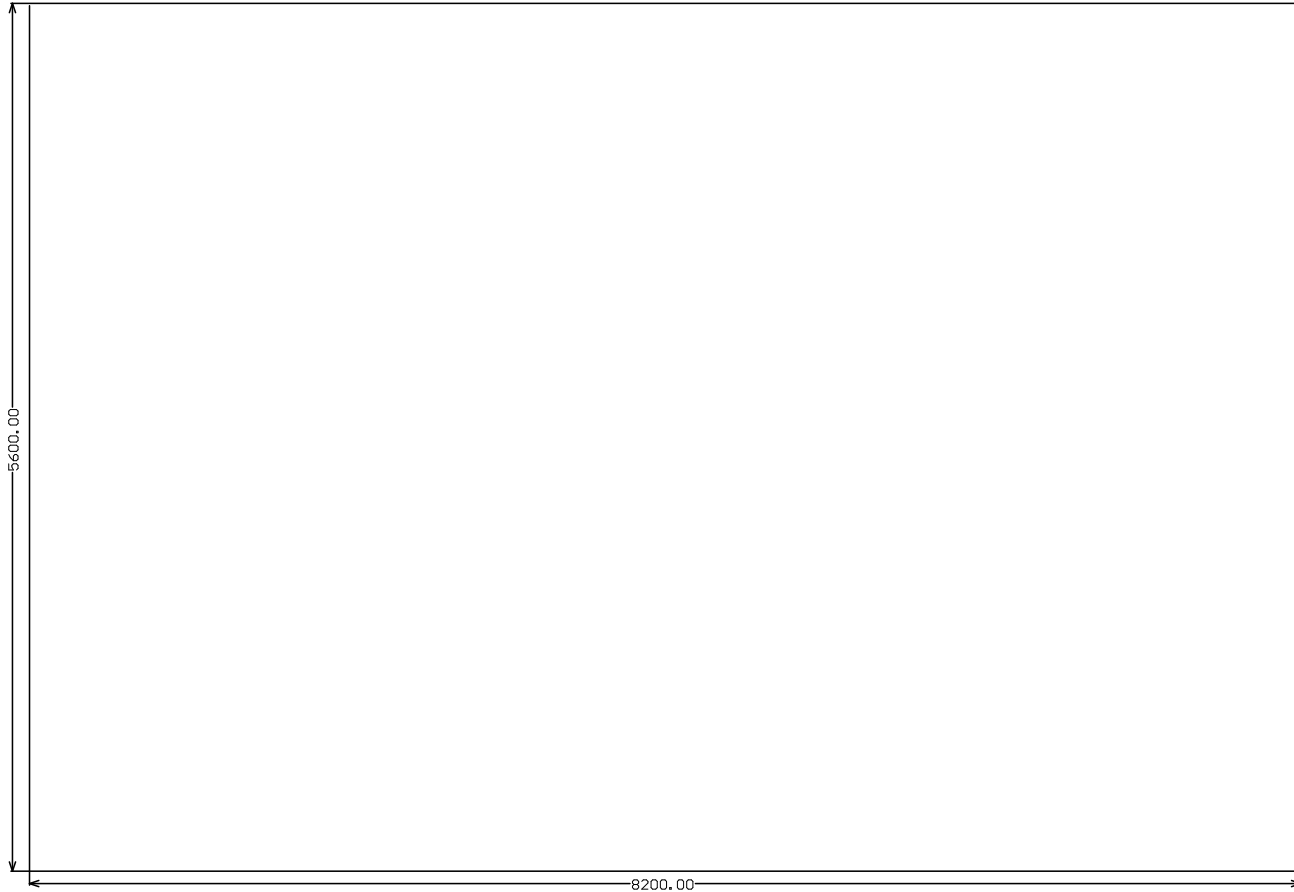
24

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01373		
PLOT NAME = Bottom Overlay	GENERATED : 2/3/2017	2:25:46 PM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	1	62.99mil (1.600mm)	NPTH	Round	Top Layer - Bottom Layer	
▽	1	70.87mil (1.800mm)	NPTH	Round	Top Layer - Bottom Layer	
⊙	123	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
▽	46	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	192	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
□	34	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	3	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	16	62.60mil (1.590mm)	PTH	Round	Top Layer - Bottom Layer	
◇	8	72.05mil (1.830mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	430 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01373		
PLOT NAME = Drill Drawing	GENERATED : 2/3/2017 2:25:47 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01373	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01373		
PLOT NAME = Board Dimensions	GENERATED : 2/3/2017	2:25:48 PM	TEXAS INSTRUMENTS

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